#### **Product profile** 1

### 1.1 General description

General-purpose pin diode in an SOD323 small plastic SMD package.

### 1.2 Features and benefits

- · Low diode capacitance: maximum 1.05 pF
- Low diode forward resistance: max. 0.7  $\Omega$
- AEC-Q101 qualified

### 1.3 Applications

· General RF applications

## **Pinning information**

Table 1. Discrete pinning

Pin	Description	Simplified outline	Graphic symbol
1	cathode		
2	anode	1 2	<b>₩</b>
		Top view	

# **Ordering information**

Table 2. Ordering information

Type number	number Package			
	Name	Description	Version	
BAP51-03	-	plastic surface-mounted package; 2 leads	SOD323	

# **Marking**

Table 3. Marking code

Table of marking code			
Type number	Marking code		
BAP51-03	A5 <sup>[1]</sup>		

<sup>[1]</sup> The marking bar indicates the cathode (see simplified outline graphic in <u>Table 1</u>).



Silicon PIN diode

# 5 Limiting values

### Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_R$	continuous reverse voltage		-	50	V
l <sub>F</sub>	continuous forward current		-	50	mA
P <sub>tot</sub>	total power dissipation	T <sub>sp</sub> ≤ 90 °C	-	500	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-65	+150	°C

### 6 Thermal characteristics

**Table 5. Thermal characteristics** 

Symbol	Parameter	Conditions	Тур	Unit
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point		120	K/W

Silicon PIN diode

### 7 Characteristics

### **Table 6. Characteristics**

 $T_i$  = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 50 mA	-	0.95	1.1	V	
V <sub>R</sub>	reverse voltage	I <sub>R</sub> = 10 μA	50	-	-	V	
I <sub>R</sub>	reverse current	V <sub>R</sub> = 50 V	-	-	100	nA	
C <sub>d</sub>	diode capacitance	f = 1 MHz (see <u>Figure 1</u> )					
		V <sub>R</sub> = 0 V	-	0.4	-	pF	
		V <sub>R</sub> = 1 V	-	0.3	0.55	pF	
		V <sub>R</sub> = 5 V	-	0.2	0.35	pF	
r <sub>D</sub>	diode forward resistance	f = 100 MHz (see <u>Figure 2</u> )					
		I <sub>F</sub> = 0.5 mA	[1] -	5.5	9	Ω	
		I <sub>F</sub> = 1 mA	[1] -	3.6	6.5	Ω	
		I <sub>F</sub> = 10 mA	[1] -	1.5	2.5	Ω	
τL	charge carrier life time	when switched from $I_F$ = 10 mA to $I_R$ = 6 mA; $R_L$ = 100 $\Omega$ ; measured at $I_R$ = 3 mA	-	550	-	ns	

<sup>[1]</sup> Guaranteed on AQL basis; inspection level S4, AQL 1.0

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# 8 Graphical data

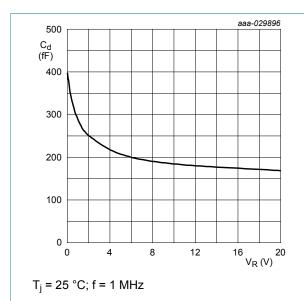
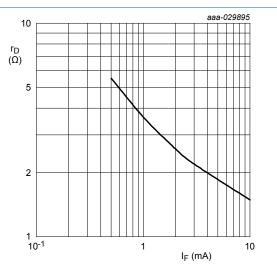
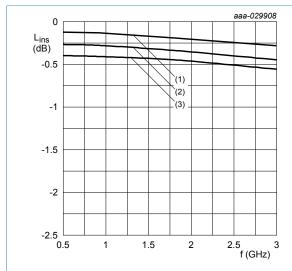


Figure 1. Diode capacitance as a function of reverse voltage (typical values)



 $T_i$  = 25 °C; f = 100 MHz.

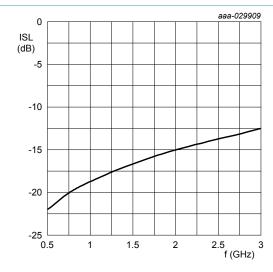
Figure 2. Diode forward resistance as a function of forward current (typical values)



Diode inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network; T<sub>amb</sub> = 25 °C

- (1)  $I_F = 10 \text{ mA}$
- (2)  $I_F = 1 \text{ mA}$
- (3)  $I_F = 0.5 \text{ mA}$

Figure 3. Insertion loss of the diode as a function of frequency (typical values)

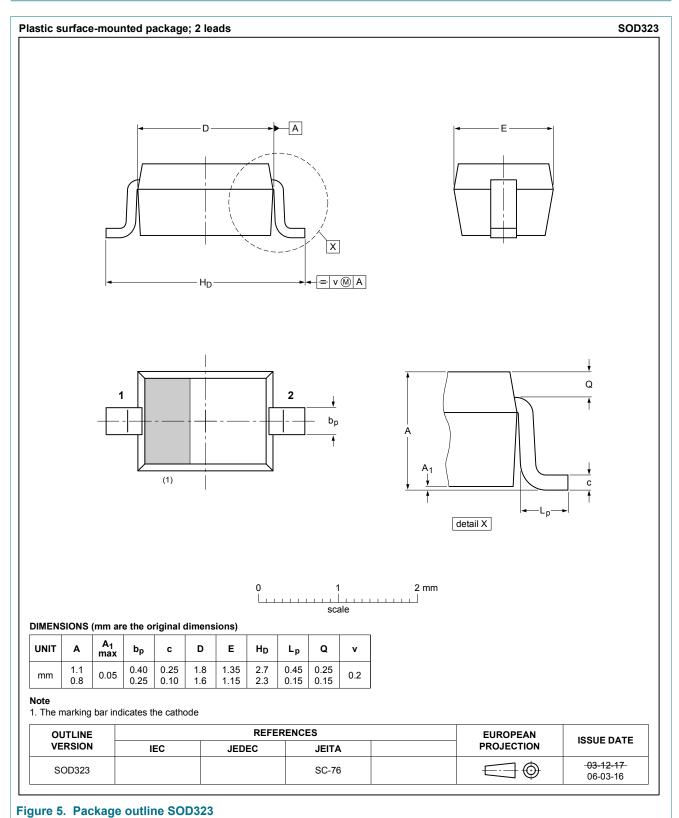


Diode zero-biased and inserted in series with a 50  $\Omega$  strip line circuit and biased via the analyzer T-network;  $T_{amb}$  = 25 °C; f = 100 MHz

Figure 4. Isolation of the diode as a function of frequency (typical values)

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# 9 Package outline



rigure 3. Fackage outline 30D323

Silicon PIN diode

# 10 Revision history

### Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BAP51-03 v.5.1	20190208	Product data sheet	-	BAP51-03 v.5
Modifications:	aligned the title or	f the data sheet with the	description on the li	nternet
BAP51-03 v.5	20181126	Product data sheet	-	BAP51-03 v.3.1
Modifications:	<ul> <li>AEC-Q101 qualification added to the features and benefits</li> <li>Section 1.2 "Features and benefits" has been updated.</li> <li>The "Legal information" pages have been updated to automotive version</li> </ul>			
BAP51-03 v.4.1	20040211	Product data sheet	-	-

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## 11 Legal information

#### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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